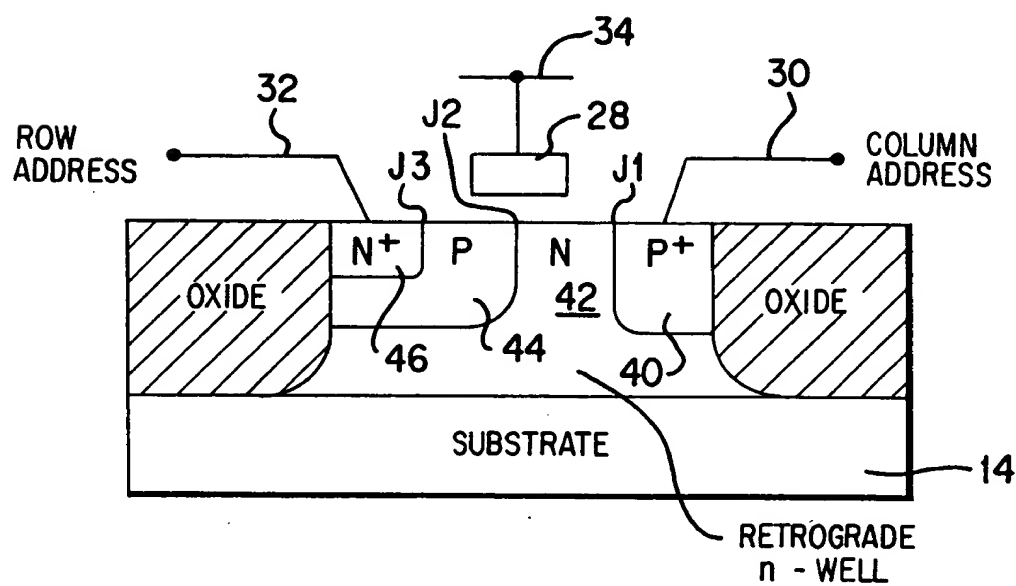
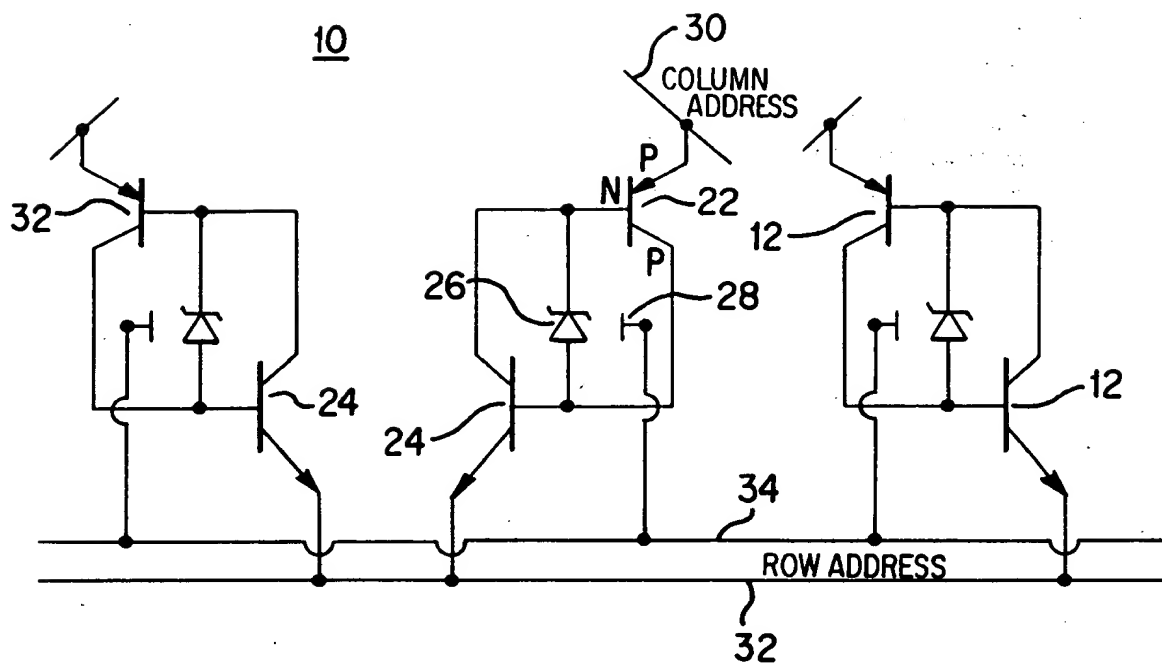




**FIG. 1**



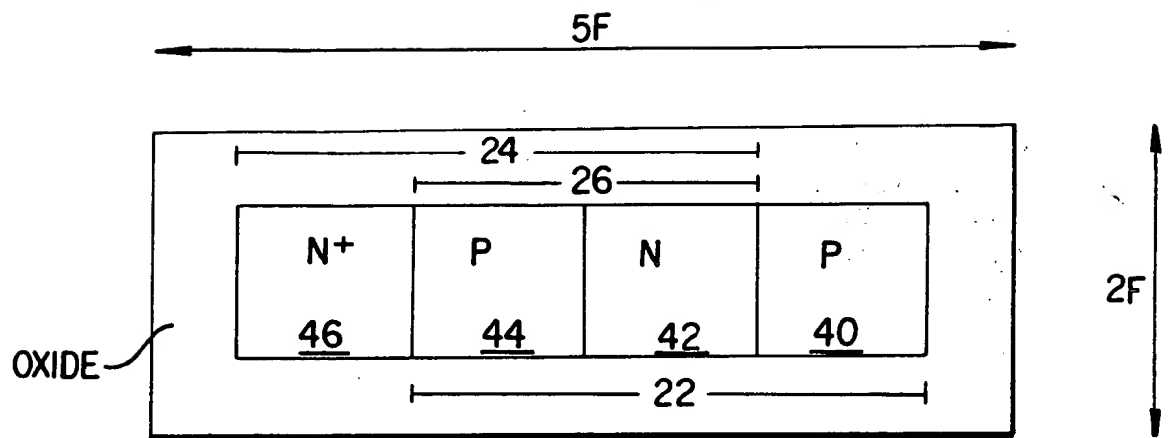


FIG. 4

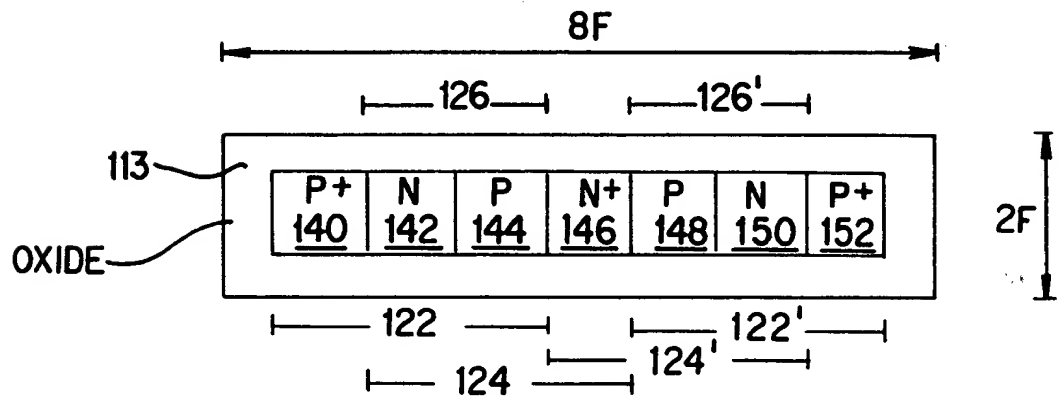


FIG. 14

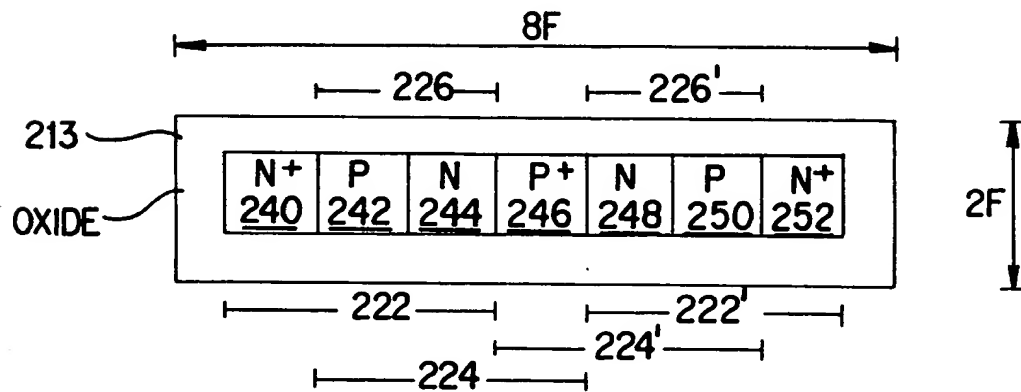


FIG. 17

A cross-sectional diagram of a 60 nm CMOS device. The structure consists of a stack of layers: P<sup>+</sup> (top), N<sup>-</sup>, P, and N<sup>+</sup> (bottom). The P<sup>+</sup> layer is connected to V<sub>DD</sub>, and the N<sup>+</sup> layer is connected to ground. A gate stack is shown on the right, with a positive gate voltage applied. The diagram highlights the 'ACCUMULATED SURFACE' at the top of the P<sup>+</sup> layer and the 'DEPLETED SURFACE' at the bottom of the N<sup>+</sup> layer. A '60 HIGH FIELD CARRIER MULTIPLICATION REGION' is indicated in the P layer. Dimensions are given as 22 nm for the N<sup>-</sup> layer and 24 nm for the P layer.

**FIG. 6**

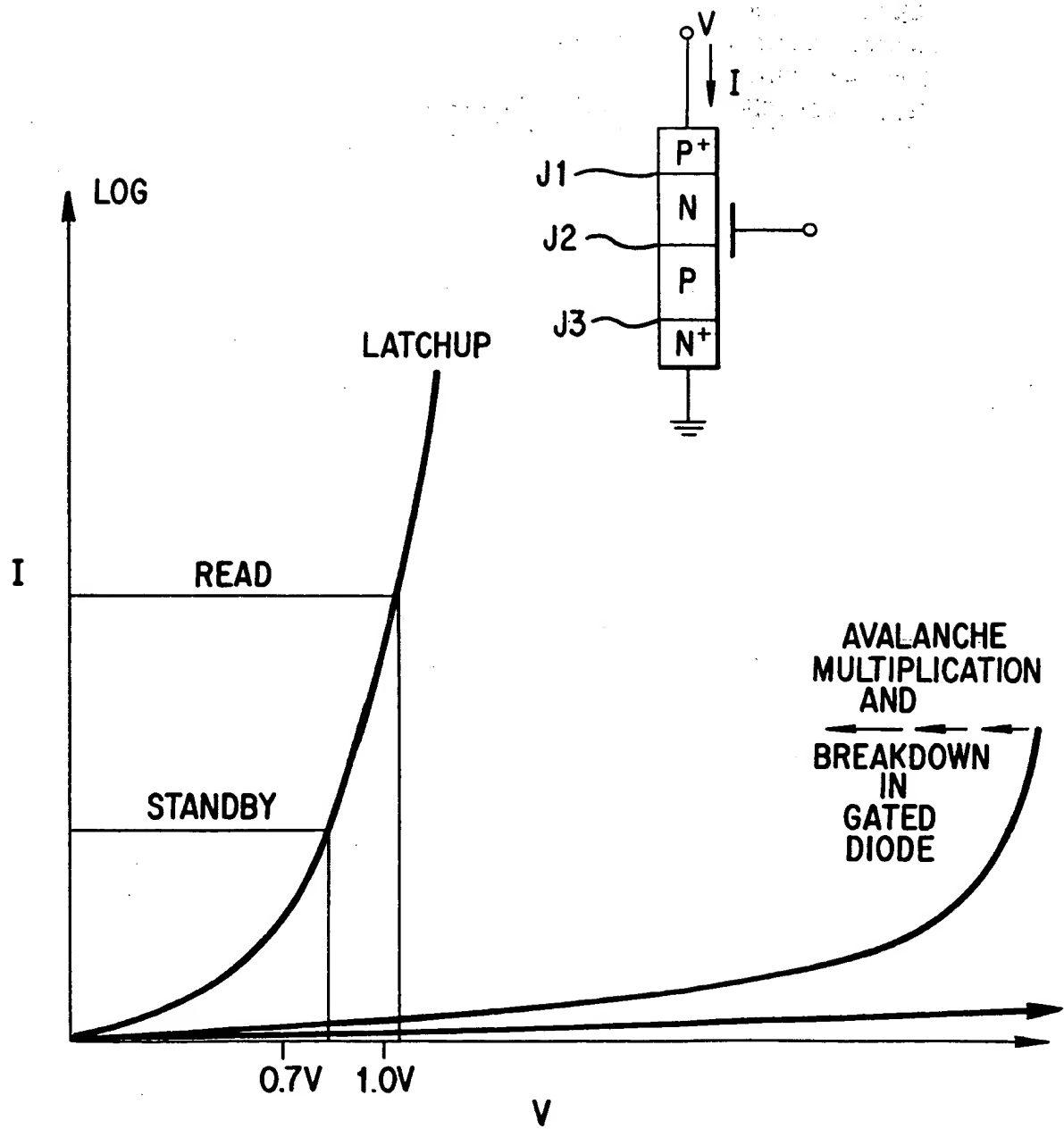


FIG. 7

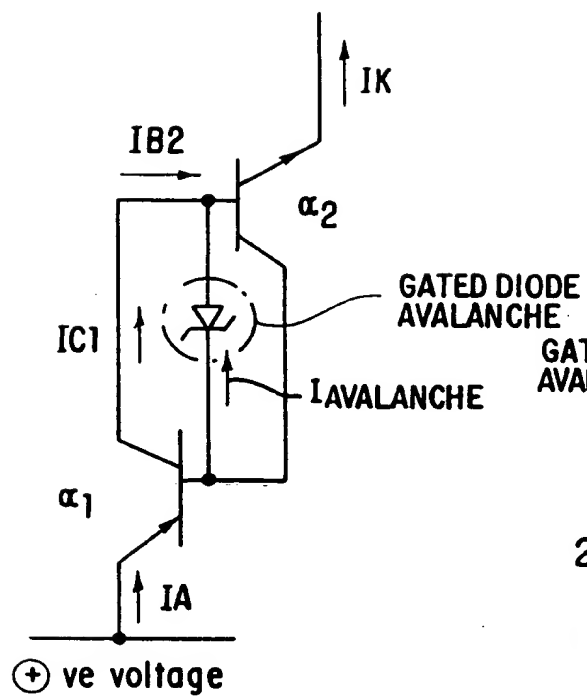


FIG. 8

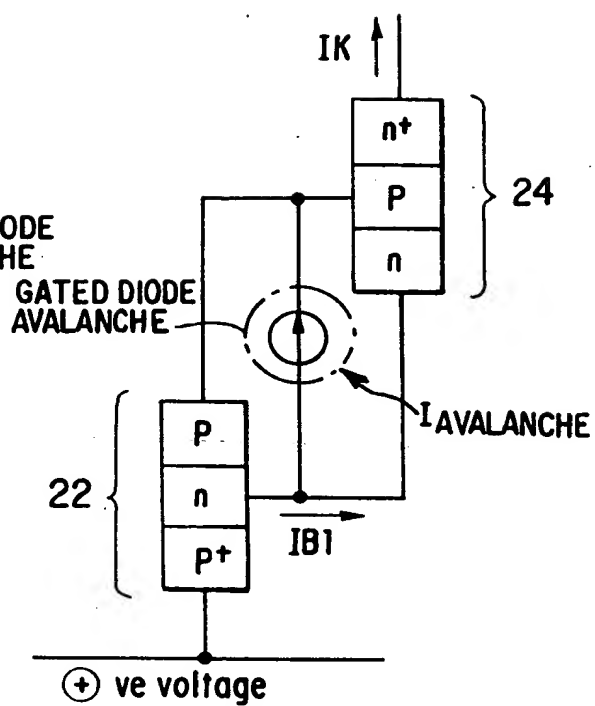


FIG. 9

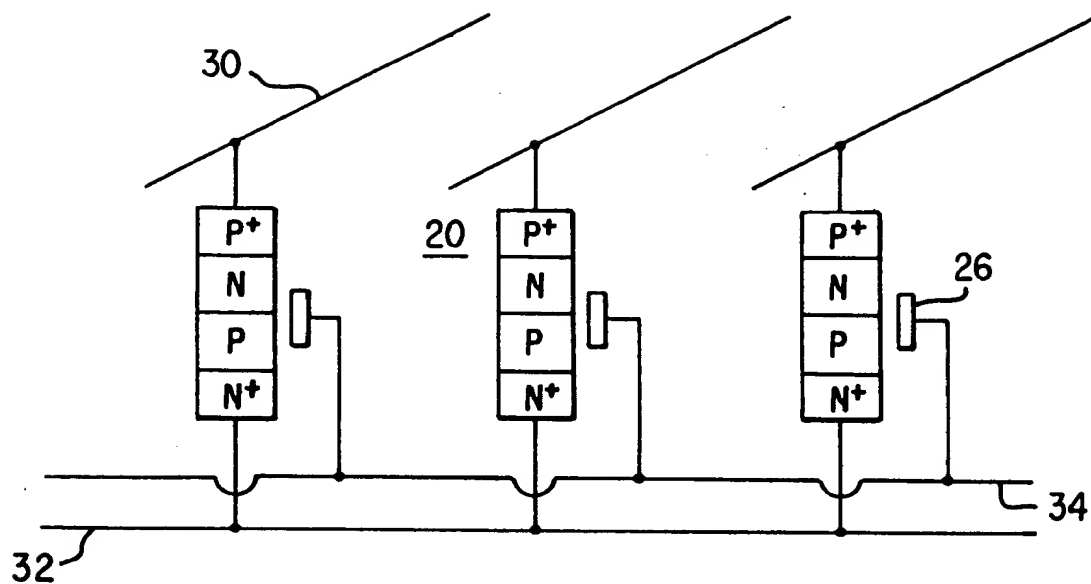


FIG. 10

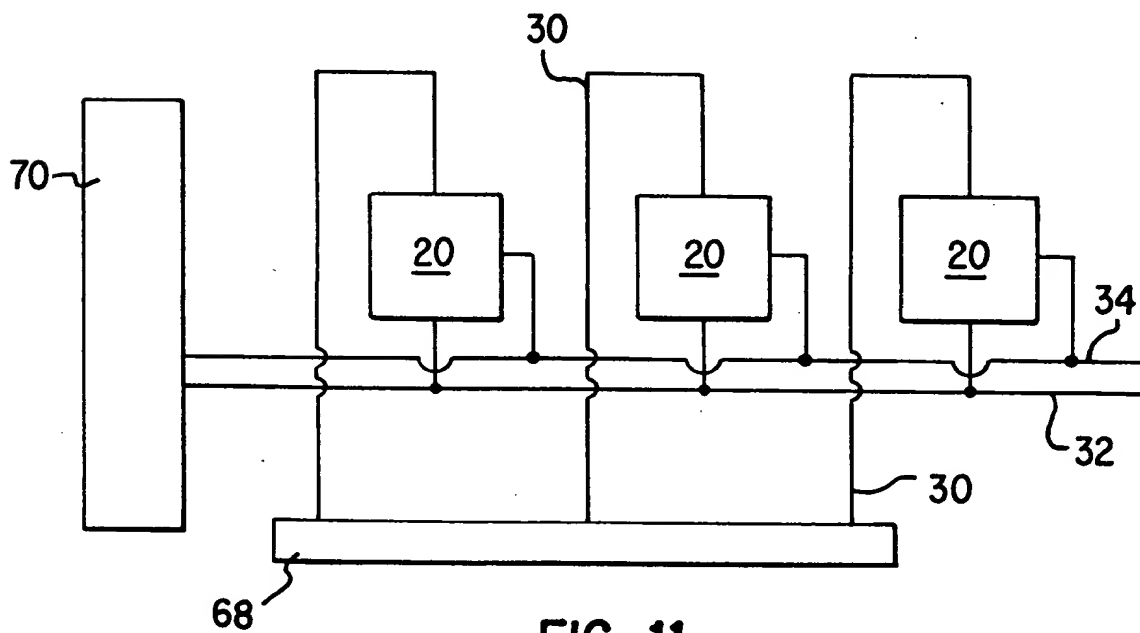


FIG. 11

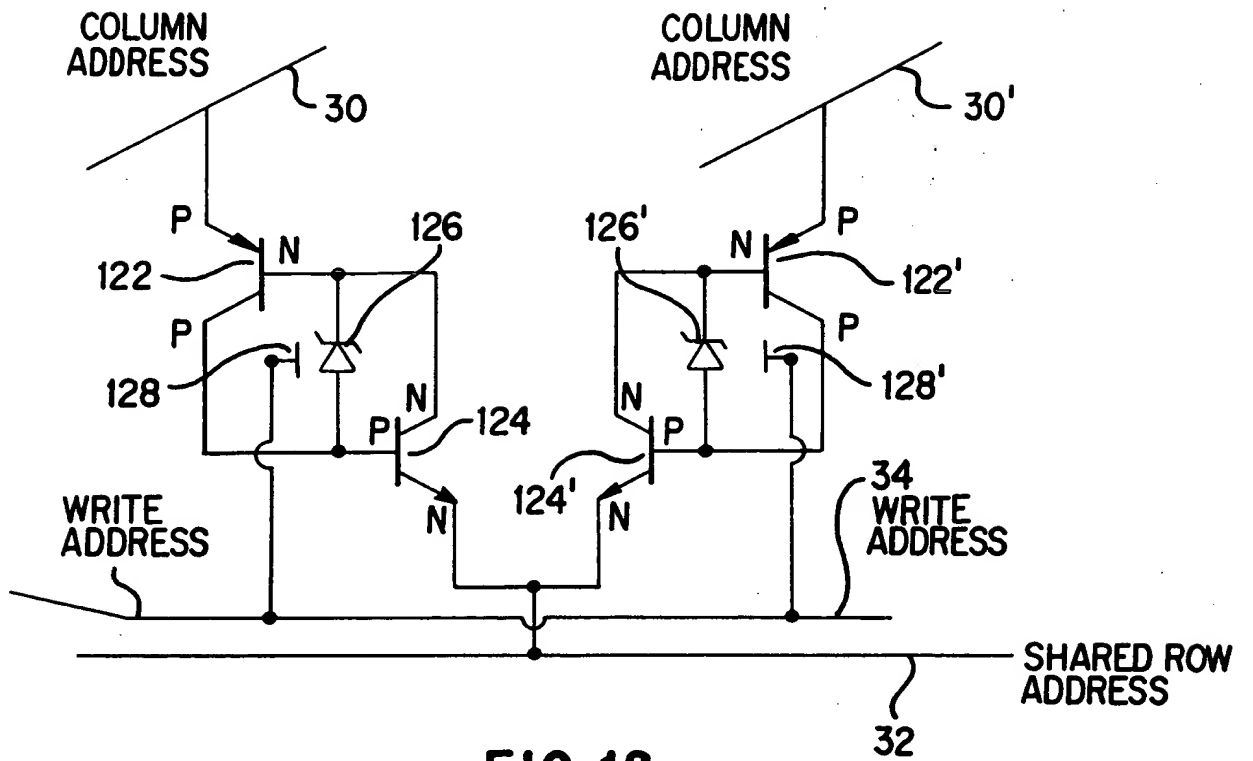


FIG. 12

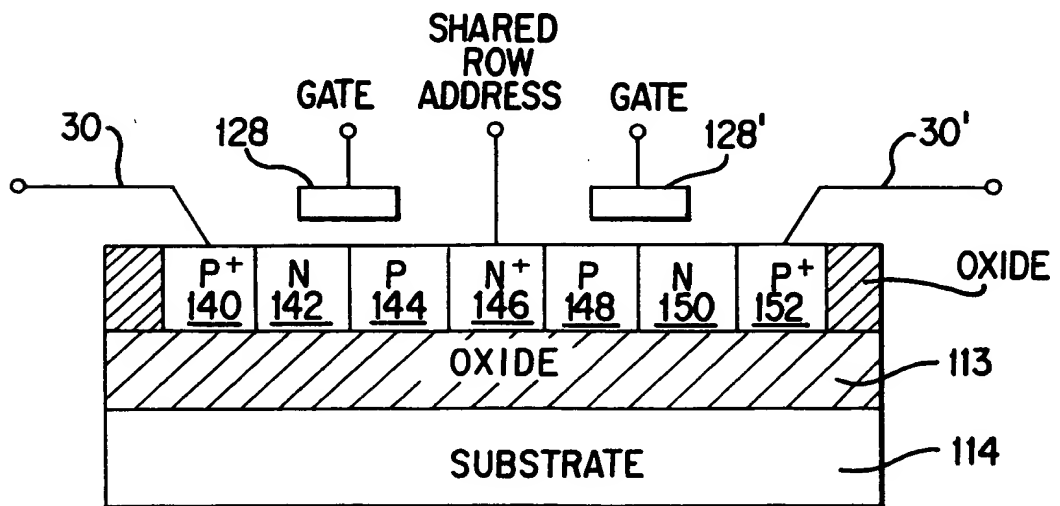


FIG. 13



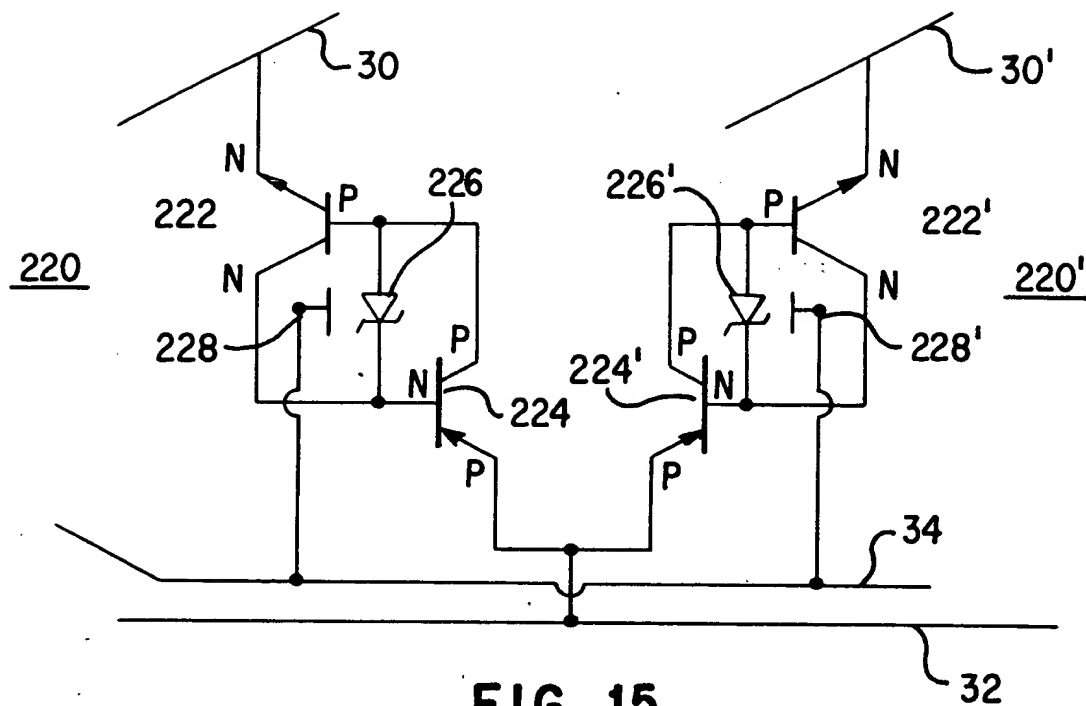


FIG. 15

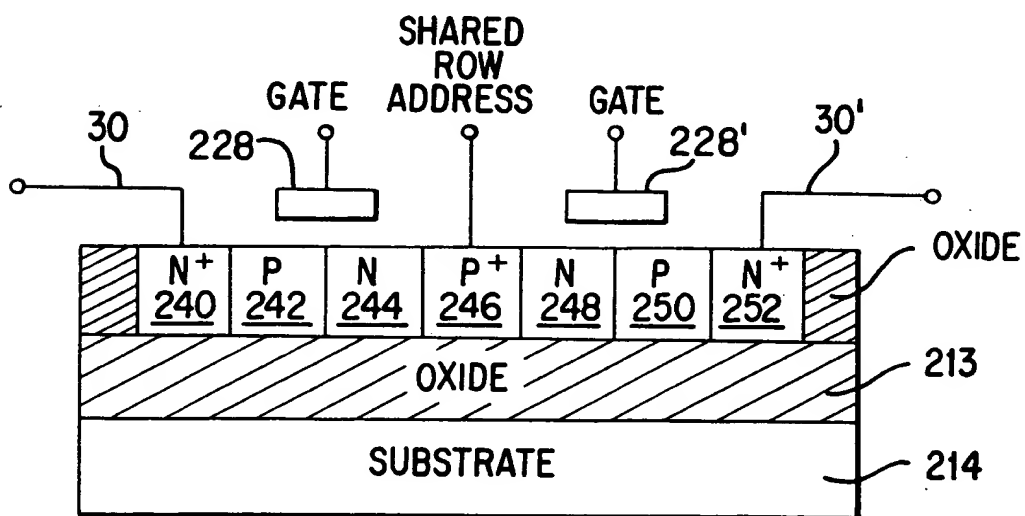


FIG. 16